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Docket No.: M4065.0239/P239

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Larry Hillyer, et al.

Application No.: 09/653,561

Group Art Unit: 2812

Filed: August 31, 2000

Examiner: H. Nguyen

For: METHOD AND MATERIAL FOR

REMOVING ETCH RESIDUE FROM HIGH ASPECT RATIO CONTACT

SURFACES

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AMENDMENT

Box Non-Fee Amendment

Commissioner for Patents Washington, DC 20231

Dear Sir:

In response to the Office Action dated July 31, 2002 (Paper No. 9), please amend the above-identified U.S. patent application as follows:

In the Claims:

Please rewrite claims 1, 6, 14, 15, 16, 17, 18, 20, 21, 22, 24, 25, 26, 29, 37 and 50 as shown in the Replacement Claims.

Please add claims 54-97 as shown in the Replacement Claims.

Please cancel claims 19, 32, 40 and 51 without prejudice to their underlying

matter.

11/27/2002 NMOHAMM1 00000074 09653561

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